RELIABILITY REPORT

FOR

MAX9144ExD

PLASTIC ENCAPSULATED DEVICES

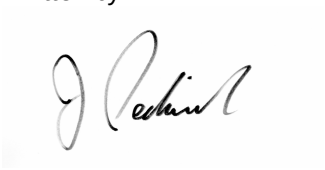
August 19, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



Jim Pedicord
Quality Assurance
Reliability Lab Manager

Reviewed by

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Quality Assurance
Executive Director

Conclusion

The MAX9144 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX9144 is a quad high-speed comparator optimized for systems powered from a 3V or 5V supply. The device combines high speed, low power, and Rail-to-Rail® inputs. Propagation delay is 40ns, while supply current is only 150µA per comparator.

The input common-mode range of the MAX9144 extends beyond both power-supply rails. The outputs pull to within 0.3V of either supply rail without external pullup circuitry, making these devices ideal for interface with both CMOS and TTL logic. All input and output pins can tolerate a continuous short-circuit fault condition to either rail. Internal hysteresis ensures clean output switching, even with slow-moving input signals.

The MAX9144 is a are higher-speed, lower-power, and lower-cost upgrade to industry-standard comparator MAX944.

The MAX9144 is available in a 14-pin TSSOP and SO packages.

B. Absolute Maximum Ratings

Item	Rating
Power Supply Ranges	
Supply Voltage (VCC to GND)	+6V
Differential Input Voltage	-0.3V to (VCC + 0.3V)
Common-Mode Input Voltage to GND	-0.3V to (VCC + 0.3V)
Input/Output Short-Circuit Duration toVCC or GND	Continuous
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation (TA = +70°C)	
14-Pin SO	667mW
14-Pin TSSOP	727mW
Derates above +70°C	
14-Pin SO	8.33mW/°C
14-Pin TSSOP	9.1mW/°C

II. Manufacturing Information

A. Description:	40ns, Low-Power, 3V/5V, Rail-to-Rail Single-Supply Comparator
B. Process:	CB30
C. Number of Device Transistors:	620
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Malaysia, Philippines or Thailand
F. Date of Initial Production:	May, 2001

III. Packaging Information

A. Package Type:	**14-Pin TSSOP**	**14-Pin NSO**
B. Lead Frame:	Copper	Copper
C. Lead Finish:	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Silver-filled Epoxy
E. Bondwire:	Gold (1.0 mil dia.)	Gold (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	Buildsheet # 05-1501-0240	Buildsheet # 05-1501-0241
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1	Level 1

IV. Die Information

A. Dimensions:	61 x 58 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Gold
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal 1: 1.4 microns Metal 2: 1.4 microns Metal 3: 3 microns (as drawn)
F. Minimum Metal Spacing:	Metal 1: 1.6 microns Metal 2: 1.6 microns Metal 3: 3 microns (as drawn)
G. Bondpad Dimensions:	2.7 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Jim Pedicord (Manager, Reliability Operations)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4389 \times 79 \times 2}$$ (Chi square value for MTTF upper limit)

Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 13.75 \times 10^{-9}$ $\lambda = 13.75$ F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. The attached Burn-In Schematic (Spec. # 06-5685) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The CM70 die type has been found to have all pins able to withstand a transient pulse of ±2500V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA.

Table 1
Reliability Evaluation Test Results

MAX9144ExD

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		79	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	TSSOP SO	77 77	0 0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

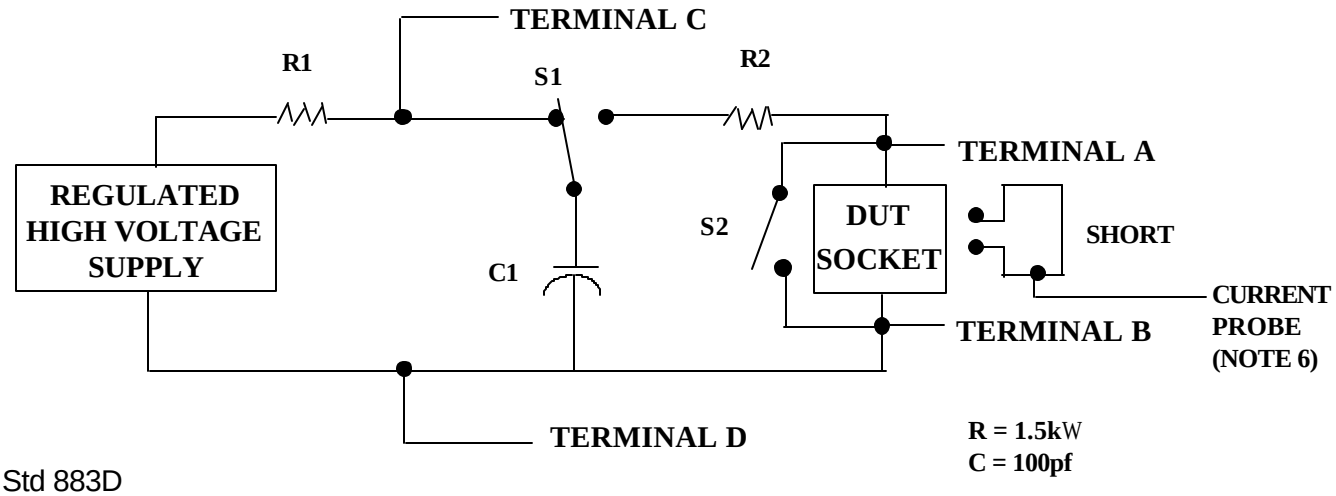
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

3.4 Pin combinations to be tested.

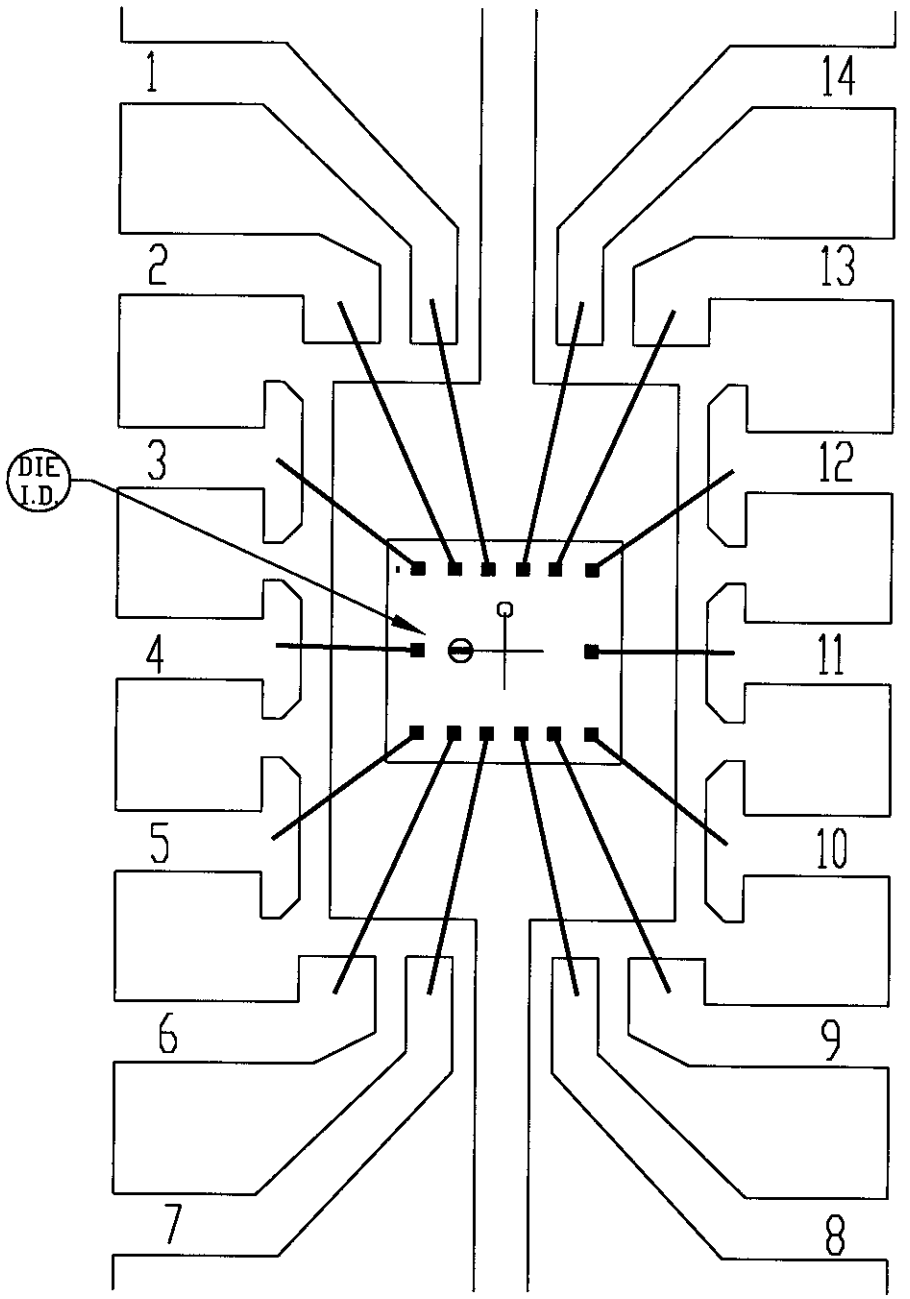
a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

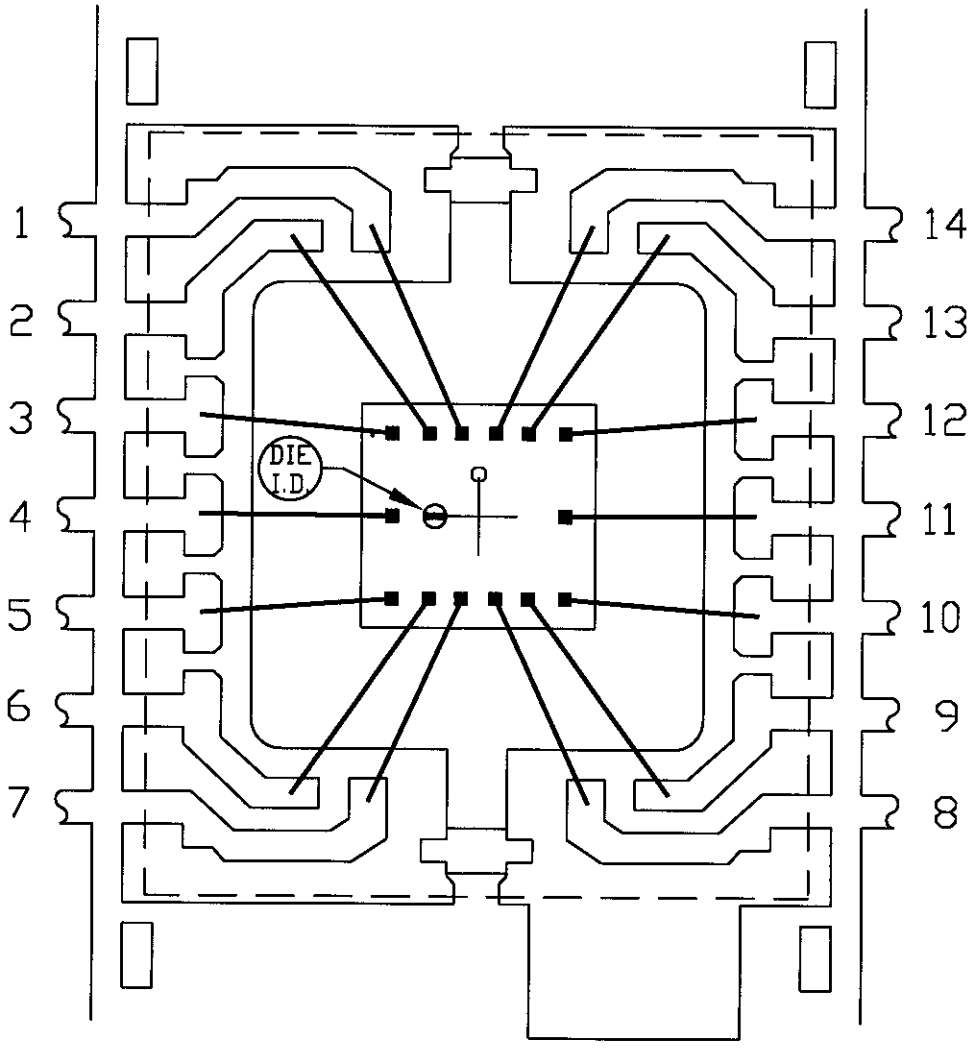
c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.



Mil Std 883D
Method 3015.7
Notice 8



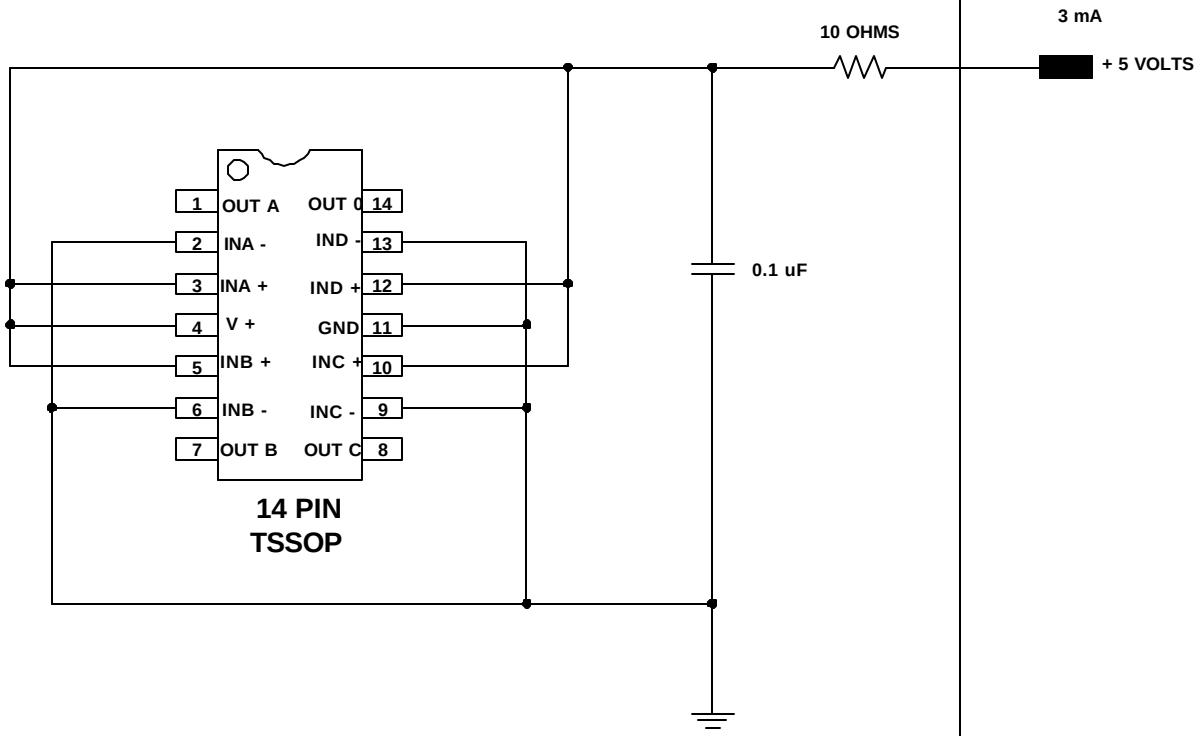
PKG. CODE: S14-1		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY
CAV./PAD SIZE: 90 X 140	PKG. DESIGN			BOND DIAGRAM #: 05-1501-0241 / REV: A



PKG. CODE: U14-1		SIGNATURES	DATE	MAXIM CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: 118x122	PKG. DESIGN			BOND DIAGRAM #: 05-1501-0240	REV: A

ONCE PER SOCKET

ONCE PER BOARD



14 PIN TSSOP

DEVICES: MAX 9144

MAX. EXPECTED CURRENT = 3 mA

NOTES: